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Details

Product Status	Obsolete
Core Processor	XC800
Core Size	8-Bit
Speed	24MHz
Connectivity	CANbus, LINbus, SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	34
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1.75K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	PG-TQFP-48
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/saf-xc886clm-8ffa-5v-ac

Summary of Features

XC886/888 Variant Devices

The XC886/888 product family features devices with different configurations, program memory sizes, package options, power supply voltage, temperature and quality profiles (Automotive or Industrial), to offer cost-effective solutions for different application requirements.

The list of XC886/888 device configurations are summarized in [Table 1](#). For each configuration, 2 types of packages are available:

- PG-TQFP-48, which is denoted by XC886 and;
- PG-TQFP-64, which is denoted by XC888.

Table 1 Device Configuration

Device Name	CAN Module	LIN BSL Support	MDU Module
XC886/888	No	No	No
XC886/888C	Yes	No	No
XC886/888CM	Yes	No	Yes
XC886/888LM	No	Yes	Yes
XC886/888CLM	Yes	Yes	Yes

Note: For variants with LIN BSL support, only LIN BSL is available regardless of the availability of the CAN module.

From these 10 different combinations of configuration and package type, each are further made available in many sales types, which are grouped according to device type, program memory sizes, power supply voltage, temperature and quality profile (Automotive or Industrial), as shown in [Table 2](#).

Table 2 Device Profile

Sales Type	Device Type	Program Memory (Kbytes)	Power Supply (V)	Temperature (°C)	Quality Profile
SAK-XC886*/888*-8FFA 5V	Flash	32	5.0	-40 to 125	Automotive
SAK-XC886*/888*-6FFA 5V	Flash	24	5.0	-40 to 125	Automotive
SAF-XC886*/888*-8FFA 5V	Flash	32	5.0	-40 to 85	Automotive
SAF-XC886*/888*-6FFA 5V	Flash	24	5.0	-40 to 85	Automotive
SAF-XC886*/888*-8FFI 5V	Flash	32	5.0	-40 to 85	Industrial
SAF-XC886*/888*-6FFI 5V	Flash	24	5.0	-40 to 85	Industrial

General Device Information
2.4 Pin Definitions and Functions

The functions and default states of the XC886/888 external pins are provided in [Table 3](#).

Table 3 Pin Definitions and Functions

Symbol	Pin Number (TQFP-48/64)	Type	Reset State	Function
P0		I/O		Port 0 Port 0 is an 8-bit bidirectional general purpose I/O port. It can be used as alternate functions for the JTAG, CCU6, UART, UART1, Timer 2, Timer 21, MultiCAN and SSC.
P0.0	11/17		Hi-Z	<div>TCK_0 JTAG Clock Input</div> <div>T12HR_1 CCU6 Timer 12 Hardware Run Input</div> <div>CC61_1 Input/Output of Capture/Compare channel 1</div> <div>CLKOUT_0 Clock Output</div> <div>RXDO_1 UART Transmit Data Output</div>
P0.1	13/21		Hi-Z	<div>TDI_0 JTAG Serial Data Input</div> <div>T13HR_1 CCU6 Timer 13 Hardware Run Input</div> <div>RXD_1 UART Receive Data Input</div> <div>RXDC1_0 MultiCAN Node 1 Receiver Input</div> <div>COUT61_1 Output of Capture/Compare channel 1</div> <div>EXF2_1 Timer 2 External Flag Output</div>
P0.2	12/18		PU	<div>CTRAP_2 CCU6 Trap Input</div> <div>TDO_0 JTAG Serial Data Output</div> <div>TXD_1 UART Transmit Data Output/Clock Output</div> <div>TXDC1_0 MultiCAN Node 1 Transmitter Output</div>
P0.3	48/63		Hi-Z	<div>SCK_1 SSC Clock Input/Output</div> <div>COUT63_1 Output of Capture/Compare channel 3</div> <div>RXDO1_0 UART1 Transmit Data Output</div>

General Device Information
Table 3 Pin Definitions and Functions (cont'd)

Symbol	Pin Number (TQFP-48/64)	Type	Reset State	Function	
P0.4	1/64		Hi-Z	MTSR_1	SSC Master Transmit Output/ Slave Receive Input
				CC62_1	Input/Output of Capture/Compare channel 2
				TXD1_0	UART1 Transmit Data Output/Clock Output
P0.5	2/1		Hi-Z	MRST_1	SSC Master Receive Input/Slave Transmit Output
				EXINT0_0	External Interrupt Input 0
				T2EX1_1	Timer 21 External Trigger Input
				RXD1_0	UART1 Receive Data Input
				COUT62_1	Output of Capture/Compare channel 2
P0.6	–/2		PU	GPIO	
P0.7	47/62		PU	CLKOUT_1	Clock Output

General Device Information
Table 3 Pin Definitions and Functions (cont'd)

Symbol	Pin Number (TQFP-48/64)	Type	Reset State	Function
P1		I/O		Port 1 Port 1 is an 8-bit bidirectional general purpose I/O port. It can be used as alternate functions for the JTAG, CCU6, UART, Timer 0, Timer 1, Timer 2, Timer 21, MultiCAN and SSC.
P1.0	26/34		PU	RXD_0 UART Receive Data Input T2EX Timer 2 External Trigger Input RXDC0_0 MultiCAN Node 0 Receiver Input
P1.1	27/35		PU	EXINT3 External Interrupt Input 3 T0_1 Timer 0 Input TDO_1 JTAG Serial Data Output TXD_0 UART Transmit Data Output/Clock Output TXDC0_0 MultiCAN Node 0 Transmitter Output
P1.2	28/36		PU	SCK_0 SSC Clock Input/Output
P1.3	29/37		PU	MTSR_0 SSC Master Transmit Output/Slave Receive Input TXDC1_3 MultiCAN Node 1 Transmitter Output
P1.4	30/38		PU	MRST_0 SSC Master Receive Input/ Slave Transmit Output EXINT0_1 External Interrupt Input 0 RXDC1_3 MultiCAN Node 1 Receiver Input
P1.5	31/39		PU	CCPOS0_1 CCU6 Hall Input 0 EXINT5 External Interrupt Input 5 T1_1 Timer 1 Input EXF2_0 Timer 2 External Flag Output RXDO_0 UART Transmit Data Output

Functional Description

code or data. Therefore, even though the ROM device contains either a 24-Kbyte or 32-Kbyte ROM, the maximum size of code that can be placed in the ROM is the given size less four bytes.

3.2.1 Memory Protection Strategy

The XC886/888 memory protection strategy includes:

- Read-out protection: The user is able to protect the contents in the Flash (for Flash devices) and ROM (for ROM devices) memory from being read
 - Flash protection is enabled by programming a valid password (8-bit non-zero value) via BSL mode 6.
 - ROM protection is fixed with the ROM mask and is always enabled.
- Flash program and erase protection: This feature is available only for Flash devices.

3.2.1.1 Flash Memory Protection

As long as a valid password is available, all external access to the device, including the Flash, will be blocked.

For additional security, the Flash hardware protection can be enabled to implement a second layer of read-out protection, as well as to enable program and erase protection.

Flash hardware protection is available only for Flash devices and comes in two modes:

- Mode 0: Only the P-Flash is protected; the D-Flash is unprotected
- Mode 1: Both the P-Flash and D-Flash are protected

The selection of each protection mode and the restrictions imposed are summarized in [Table 4](#).

Table 4 Flash Protection Modes

Flash Protection	Without hardware protection		With hardware protection	
Hardware Protection Mode	-	0	1	
Activation	Program a valid password via BSL mode 6			
Selection	Bit 4 of password = 0	Bit 4 of password = 1 MSB of password = 0	Bit 4 of password = 1 MSB of password = 1	
P-Flash contents can be read by	Read instructions in any program memory	Read instructions in the P-Flash	Read instructions in the P-Flash or D-Flash	
External access to P-Flash	Not possible	Not possible	Not possible	

Functional Description

SYSCON0

System Control Register 0

Reset Value: 04_H

7	6	5	4	3	2	1	0
0			IMODE	0	1	0	RMAP
r			rw	r	r	r	rw

Field	Bits	Type	Description
RMAP	0	rw	Interrupt Node XINTR0 Enable 0 The access to the standard SFR area is enabled 1 The access to the mapped SFR area is enabled
1	2	r	Reserved Returns 1 if read; should be written with 1.
0	[7:5], 3,1	r	Reserved Returns 0 if read; should be written with 0.

Note: The RMAP bit should be cleared/set by ANL or ORL instructions.

3.2.2.2 Address Extension by Paging

Address extension is further performed at the module level by paging. With the address extension by mapping, the XC886/888 has a 256-SFR address range. However, this is still less than the total number of SFRs needed by the on-chip peripherals. To meet this requirement, some peripherals have a built-in local address extension mechanism for increasing the number of addressable SFRs. The extended address range is not directly controlled by the CPU instruction itself, but is derived from bit field PAGE in the module page register MOD_PAGE. Hence, the bit field PAGE must be programmed before accessing the SFR of the target module. Each module may contain a different number of pages and a different number of SFRs per page, depending on the specific requirement. Besides setting the correct RMAP bit value to select the SFR area, the user must also ensure that a valid PAGE is selected to target the desired SFR. A page inside the extended address range can be selected as shown in [Figure 9](#).

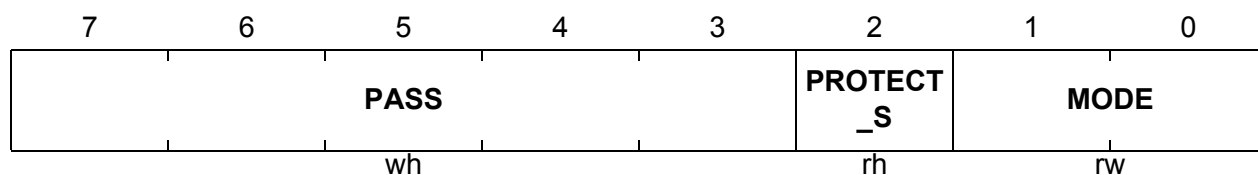
Functional Description

3.2.3.1 Password Register

PASSWD

Password Register

Reset Value: 07_H



Field	Bits	Type	Description
MODE	[1:0]	rw	Bit Protection Scheme Control Bits 00 Scheme disabled - direct access to the protected bits is allowed. 11 Scheme enabled - the bit field PASS has to be written with the passwords to open and close the access to protected bits. (default) Others: Scheme Enabled. These two bits cannot be written directly. To change the value between 11 _B and 00 _B , the bit field PASS must be written with 11000 _B ; only then, will the MODE[1:0] be registered.
PROTECT_S	2	rh	Bit Protection Signal Status Bit This bit shows the status of the protection. 0 Software is able to write to all protected bits. 1 Software is unable to write to any protected bits.
PASS	[7:3]	wh	Password Bits The Bit Protection Scheme only recognizes three patterns. 11000 _B Enables writing of the bit field MODE. 10011 _B Opens access to writing of all protected bits. 10101 _B Closes access to writing of all protected bits

Functional Description

3.2.4.8 Timer 2 Registers

The Timer 2 SFRs can be accessed in the standard memory area (RMAP = 0).

Table 12 T2 Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
C0 _H	T2_T2CON Reset: 00_H Timer 2 Control Register	Bit Field	TF2	EXF2	0		EXEN 2	TR2	C/ $\overline{T2}$	CP/ RL2
		Type	rwh	rwh	r		rw	rwh	rw	rw
C1 _H	T2_T2MOD Reset: 00_H Timer 2 Mode Register	Bit Field	T2RE GS	T2RH EN	EDGE SEL	PREN	T2PRE			DCEN
		Type	rw	rw	rw	rw	rw	rw	rw	rw
C2 _H	T2_RC2L Reset: 00_H Timer 2 Reload/Capture Register Low	Bit Field	RC2							
		Type	rwh							
C3 _H	T2_RC2H Reset: 00_H Timer 2 Reload/Capture Register High	Bit Field	RC2							
		Type	rwh							
C4 _H	T2_T2L Reset: 00_H Timer 2 Register Low	Bit Field	THL2							
		Type	rwh							
C5 _H	T2_T2H Reset: 00_H Timer 2 Register High	Bit Field	THL2							
		Type	rwh							

3.2.4.9 Timer 21 Registers

The Timer 21 SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 13 T21 Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 1										
C0 _H	T21_T2CON Reset: 00_H Timer 2 Control Register	Bit Field	TF2	EXF2	0		EXEN 2	TR2	C/ $\overline{T2}$	CP/ RL2
		Type	rwh	rwh	r		rw	rwh	rw	rw
C1 _H	T21_T2MOD Reset: 00_H Timer 2 Mode Register	Bit Field	T2RE GS	T2RH EN	EDGE SEL	PREN	T2PRE			DCEN
		Type	rw	rw	rw	rw	rw	rw	rw	rw
C2 _H	T21_RC2L Reset: 00_H Timer 2 Reload/Capture Register Low	Bit Field	RC2							
		Type	rwh							
C3 _H	T21_RC2H Reset: 00_H Timer 2 Reload/Capture Register High	Bit Field	RC2							
		Type	rwh							
C4 _H	T21_T2L Reset: 00_H Timer 2 Register Low	Bit Field	THL2							
		Type	rwh							

Functional Description
Table 14 CCU6 Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
FB _H	CCU6_CC60RH Reset: 00_H Capture/Compare Register for Channel CC60 High	Bit Field	CC60VH							
		Type	rh							
FC _H	CCU6_CC61RL Reset: 00_H Capture/Compare Register for Channel CC61 Low	Bit Field	CC61VL							
		Type	rh							
FD _H	CCU6_CC61RH Reset: 00_H Capture/Compare Register for Channel CC61 High	Bit Field	CC61VH							
		Type	rh							
FE _H	CCU6_CC62RL Reset: 00_H Capture/Compare Register for Channel CC62 Low	Bit Field	CC62VL							
		Type	rh							
FF _H	CCU6_CC62RH Reset: 00_H Capture/Compare Register for Channel CC62 High	Bit Field	CC62VH							
		Type	rh							
RMAP = 0, PAGE 2										
9A _H	CCU6_T12MSELL Reset: 00_H T12 Capture/Compare Mode Select Register Low	Bit Field	MSEL61				MSEL60			
		Type	rw				rw			
9B _H	CCU6_T12MSELH Reset: 00_H T12 Capture/Compare Mode Select Register High	Bit Field	DBYP	HSYNC			MSEL62			
		Type	rw	rw			rw			
9C _H	CCU6_IENL Reset: 00_H Capture/Compare Interrupt Enable Register Low	Bit Field	ENT1 2 PM	ENT1 2 OM	ENCC 62F	ENCC 62R	ENCC 61F	ENCC 61R	ENCC 60F	ENCC 60R
		Type	rw	rw	rw	rw	rw	rw	rw	rw
9D _H	CCU6_IENH Reset: 00_H Capture/Compare Interrupt Enable Register High	Bit Field	EN STR	EN IDLE	EN WHE	EN CHE	0	EN TRPF	ENT1 3PM	ENT1 3CM
		Type	rw	rw	rw	rw	r	rw	rw	rw
9E _H	CCU6_INPL Reset: 40_H Capture/Compare Interrupt Node Pointer Register Low	Bit Field	INPCHE		INPCC62		INPCC61		INPCC60	
		Type	rw		rw		rw		rw	
9F _H	CCU6_INPH Reset: 39_H Capture/Compare Interrupt Node Pointer Register High	Bit Field	0		INPT13		INPT12		INPERR	
		Type	r		rw		rw		rw	
A4 _H	CCU6_ISSL Reset: 00_H Capture/Compare Interrupt Status Set Register Low	Bit Field	ST12 PM	ST12 OM	SCC6 2F	SCC6 2R	SCC6 1F	SCC6 1R	SCC6 0F	SCC6 0R
		Type	w	w	w	w	w	w	w	w
A5 _H	CCU6_ISSH Reset: 00_H Capture/Compare Interrupt Status Set Register High	Bit Field	SSTR	SIDLE	SWHE	SCHE	SWH C	STRP F	ST13 PM	ST13 CM
		Type	w	w	w	w	w	w	w	w
A6 _H	CCU6_PSLR Reset: 00_H Passive State Level Register	Bit Field	PSL63	0	PSL					
		Type	rwh	r	rwh					
A7 _H	CCU6_MCMCTR Reset: 00_H Multi-Channel Mode Control Register	Bit Field	0		SWSYN		0	SWSEL		
		Type	r		rw		r	rw		
FA _H	CCU6_TCTR2L Reset: 00_H Timer Control Register 2 Low	Bit Field	0	T13TED		T13TEC			T13 SSC	T12 SSC
		Type	r	rw		rw			rw	rw

Functional Description

3.2.4.12 SSC Registers

The SSC SFRs can be accessed in the standard memory area (RMAP = 0).

Table 16 SSC Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
A9 _H	SSC_PISEL Reset: 00 _H Port Input Select Register	Bit Field	0					CIS	SIS	MIS
		Type	r					rw	rw	rw
AA _H	SSC_CONL Reset: 00 _H Control Register Low Programming Mode	Bit Field	LB	PO	PH	HB	BM			
		Type	rw	rw	rw	rw	rw			
AA _H	SSC_CONL Reset: 00 _H Control Register Low Operating Mode	Bit Field	0				BC			
		Type	r				rh			
AB _H	SSC_CONH Reset: 00 _H Control Register High Programming Mode	Bit Field	EN	MS	0	AREN	BEN	PEN	REN	TEN
		Type	rw	rw	r	rw	rw	rw	rw	rw
AB _H	SSC_CONH Reset: 00 _H Control Register High Operating Mode	Bit Field	EN	MS	0	BSY	BE	PE	RE	TE
		Type	rw	rw	r	rh	rwh	rwh	rwh	rwh
AC _H	SSC_TBL Reset: 00 _H Transmitter Buffer Register Low	Bit Field	TB_VALUE							
		Type	rw							
AD _H	SSC_RBL Reset: 00 _H Receiver Buffer Register Low	Bit Field	RB_VALUE							
		Type	rh							
AE _H	SSC_BRL Reset: 00 _H Baud Rate Timer Reload Register Low	Bit Field	BR_VALUE							
		Type	rw							
AF _H	SSC_BRH Reset: 00 _H Baud Rate Timer Reload Register High	Bit Field	BR_VALUE							
		Type	rw							

3.2.4.13 MultiCAN Registers

The MultiCAN SFRs can be accessed in the standard memory area (RMAP = 0).

Table 17 CAN Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
D8 _H	ADCON Reset: 00 _H CAN Address/Data Control Register	Bit Field	V3	V2	V1	V0	AUAD		BSY	RWEN
		Type	rw	rw	rw	rw	rw		rh	rw
D9 _H	ADL Reset: 00 _H CAN Address Register Low	Bit Field	CA9	CA8	CA7	CA6	CA5	CA4	CA3	CA2
		Type	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh
DA _H	ADH Reset: 00 _H CAN Address Register High	Bit Field	0				CA13	CA12	CA11	CA10
		Type	r				rwh	rwh	rwh	rwh

Functional Description

Table 19 shows the Flash data retention and endurance targets.

Table 19 Flash Data Retention and Endurance (Operating Conditions apply)

Retention	Endurance ¹⁾	Size	Remarks
Program Flash			
20 years	1,000 cycles	up to 32 Kbytes ²⁾	for 32-Kbyte Variant
20 years	1,000 cycles	up to 24 Kbytes ²⁾	for 24-Kbyte Variant
Data Flash			
20 years	1,000 cycles	4 Kbytes	
5 years	10,000 cycles	1 Kbyte	
2 years	70,000 cycles	512 bytes	
2 years	100,000 cycles	128 bytes	

- 1) One cycle refers to the programming of all wordlines in a sector and erasing of sector. The Flash endurance data specified in **Table 19** is valid only if the following conditions are fulfilled:
 - the maximum number of erase cycles per Flash sector must not exceed 100,000 cycles.
 - the maximum number of erase cycles per Flash bank must not exceed 300,000 cycles.
 - the maximum number of program cycles per Flash bank must not exceed 2,500,000 cycles.
- 2) If no Flash is used for data, the Program Flash size can be up to the maximum Flash size available in the device variant. Having more Data Flash will mean less Flash is available for Program Flash.

3.3.1 Flash Bank Sectorization

The XC886/888 product family offers Flash devices with either 24 Kbytes or 32 Kbytes of embedded Flash memory. Each Flash device consists of Program Flash (P-Flash) and Data Flash (D-Flash) bank(s) with different sectorization shown in **Figure 11**. Both types can be used for code and data storage. The label “Data” neither implies that the D-Flash is mapped to the data memory region, nor that it can only be used for data storage. It is used to distinguish the different Flash bank sectorizations.

The 32-Kbyte Flash device consists of 6 P-Flash and 2 D-Flash banks, while the 24-Kbyte Flash device consists of also of 6 P-Flash banks but with the upper 2 banks only 2 Kbytes each, and only 1 D-Flash bank. The XC886/888 ROM devices offer a single 4-Kbyte D-Flash bank.

The P-Flash banks are always grouped in pairs. As such, the P-Flash banks are also sometimes referred to as P-Flash bank pair. Each sector in a P-Flash bank is grouped with the corresponding sector from the other bank within a bank pair to form a P-Flash bank pair sector.

Functional Description

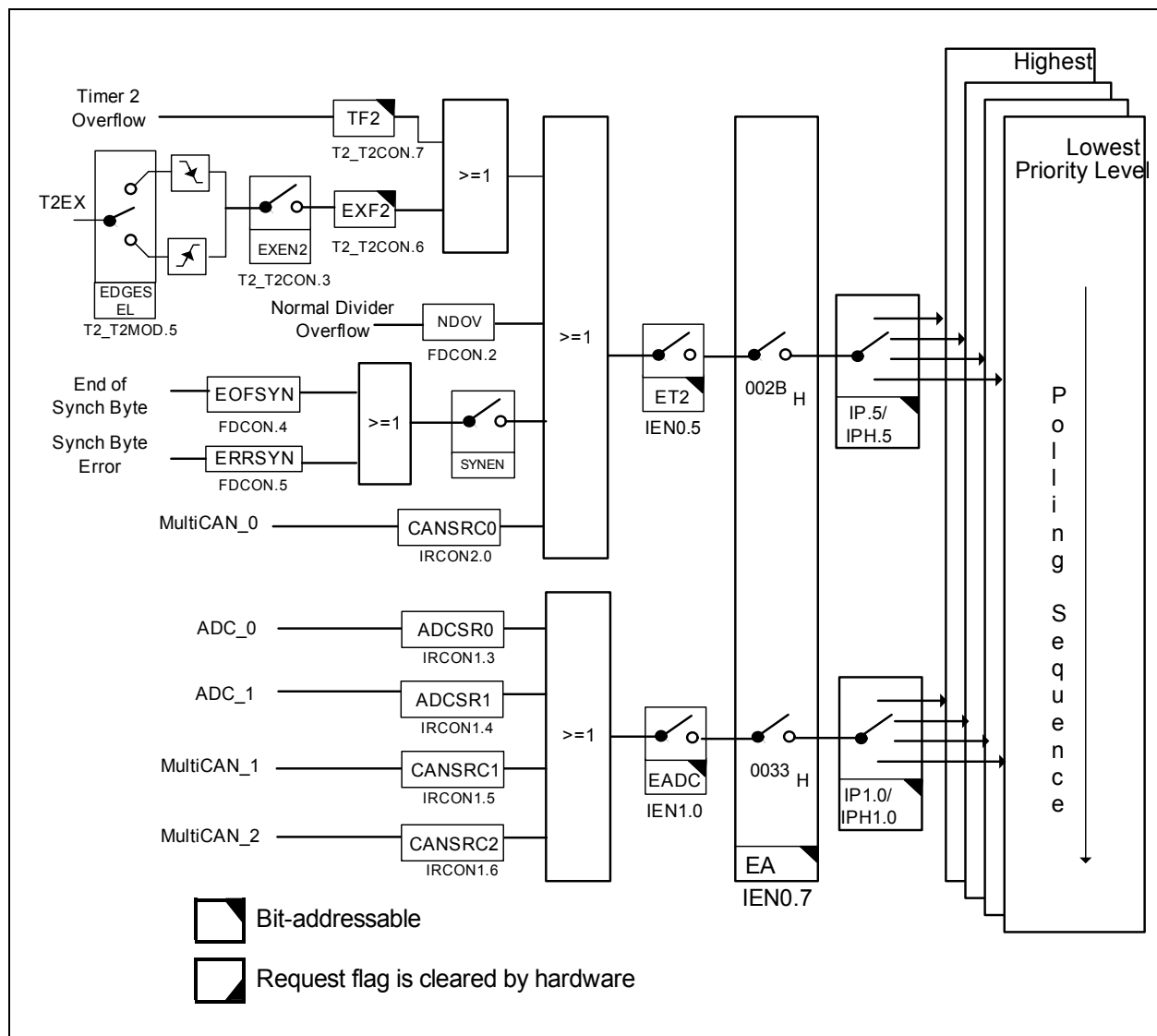


Figure 15 Interrupt Request Sources (Part 2)

Functional Description

3.11 Multiplication/Division Unit

The Multiplication/Division Unit (MDU) provides fast 16-bit multiplication, 16-bit and 32-bit division as well as shift and normalize features. It has been integrated to support the XC886/888 Core in real-time control applications, which require fast mathematical computations.

Features

- Fast signed/unsigned 16-bit multiplication
- Fast signed/unsigned 32-bit divide by 16-bit and 16-bit divide by 16-bit operations
- 32-bit unsigned normalize operation
- 32-bit arithmetic/logical shift operations

Table 28 specifies the number of clock cycles used for calculation in various operations.

Table 28 MDU Operation Characteristics

Operation	Result	Remainder	No. of Clock Cycles used for calculation
Signed 32-bit/16-bit	32-bit	16-bit	33
Signed 16-bit/16bit	16-bit	16-bit	17
Signed 16-bit x 16-bit	32-bit	-	16
Unsigned 32-bit/16-bit	32-bit	16-bit	32
Unsigned 16-bit/16-bit	16-bit	16-bit	16
Unsigned 16-bit x 16-bit	32-bit	-	16
32-bit normalize	-	-	No. of shifts + 1 (Max. 32)
32-bit shift L/R	-	-	No. of shifts + 1 (Max. 32)

Functional Description

3.15 LIN Protocol

The UART module can be used to support the Local Interconnect Network (LIN) protocol for both master and slave operations. The LIN baud rate detection feature, which consists of the hardware logic for Break and Synch Byte detection, provides the capability to detect the baud rate within LIN protocol using Timer 2. This allows the UART to be synchronized to the LIN baud rate for data transmission and reception.

Note: The LIN baud rate detection feature is available for use only with UART. To use UART1 for LIN communication, software has to be implemented to detect the Break and Synch Byte.

LIN is a holistic communication concept for local interconnected networks in vehicles. The communication is based on the SCI (UART) data format, a single-master/multiple-slave concept, a clock synchronization for nodes without stabilized time base. An attractive feature of LIN is self-synchronization of the slave nodes without a crystal or ceramic resonator, which significantly reduces the cost of hardware platform. Hence, the baud rate must be calculated and returned with every message frame.

The structure of a LIN frame is shown in [Figure 31](#). The frame consists of the:

- Header, which comprises a Break (13-bit time low), Synch Byte (55_H), and ID field
- Response time
- Data bytes (according to UART protocol)
- Checksum

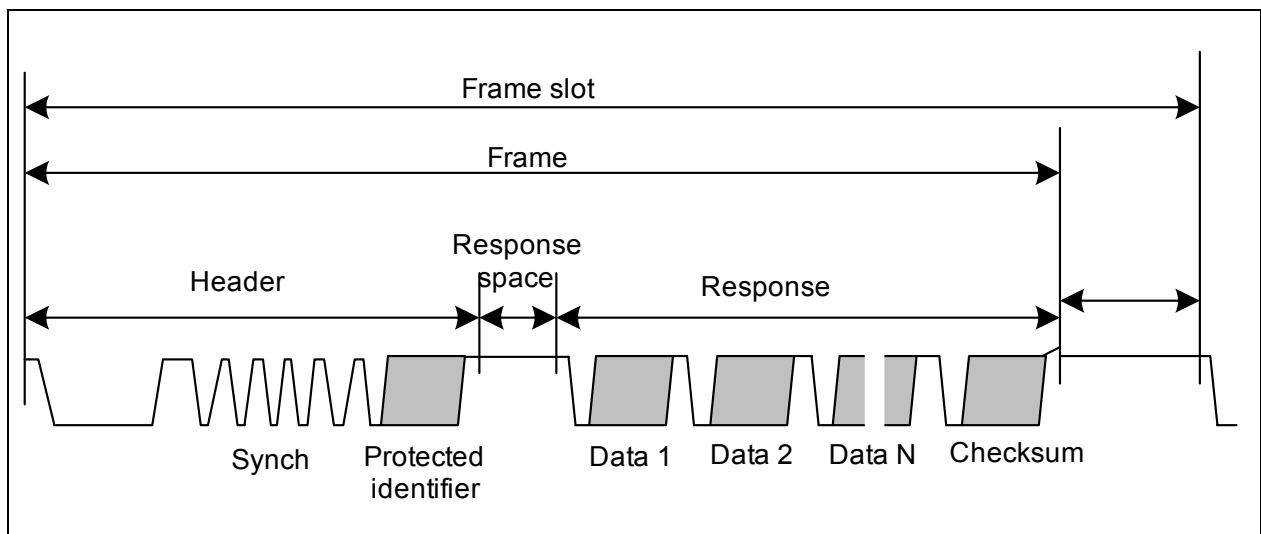


Figure 31 Structure of LIN Frame

3.15.1 LIN Header Transmission

LIN header transmission is only applicable in master mode. In the LIN communication, a master task decides when and which frame is to be transferred on the bus. It also identifies a slave task to provide the data transported by each frame. The information

Functional Description

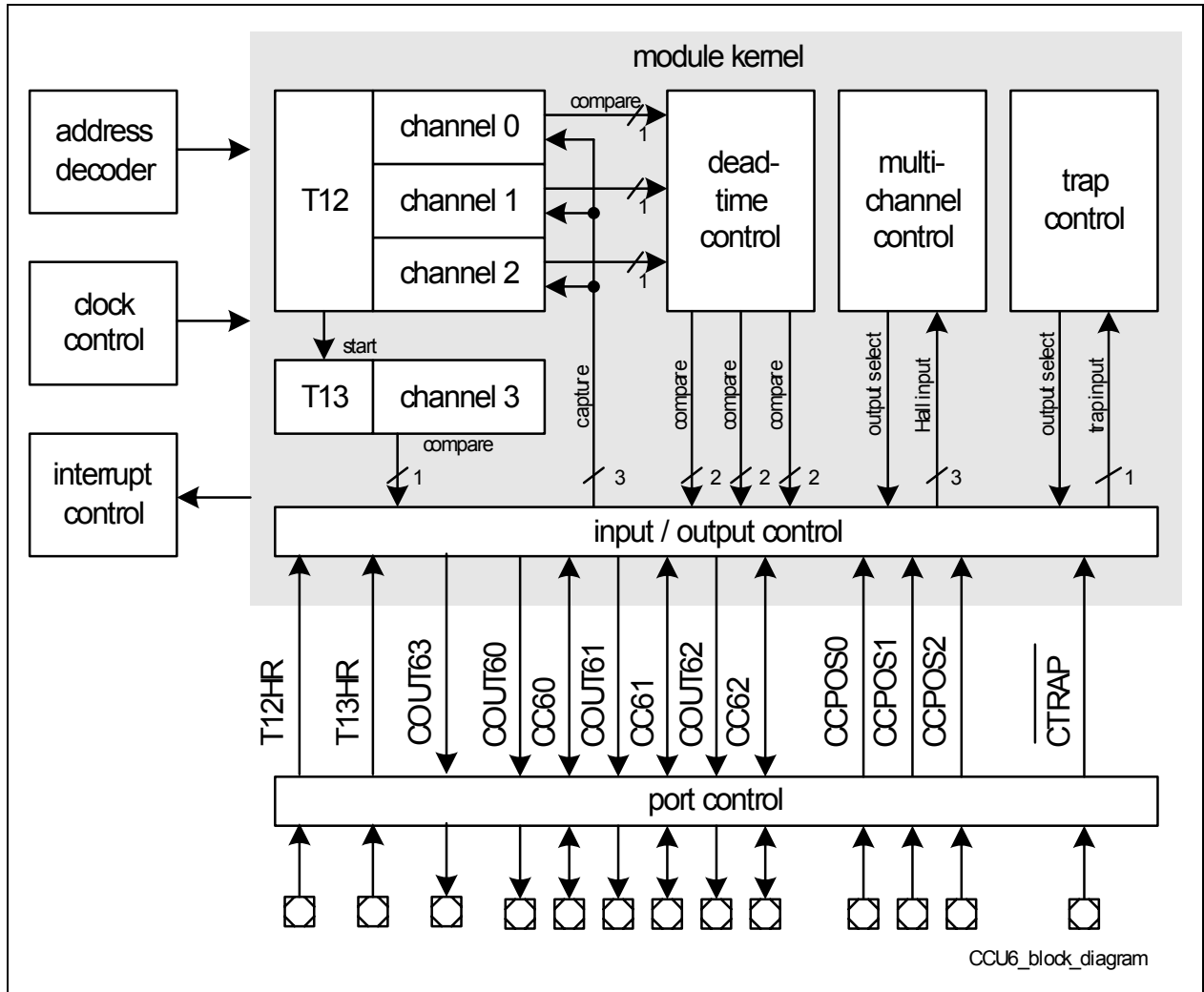


Figure 33 CCU6 Block Diagram

Functional Description

GLOBCTR. A prescaling ratio of 32 can be selected when the maximum performance of the ADC is not required.

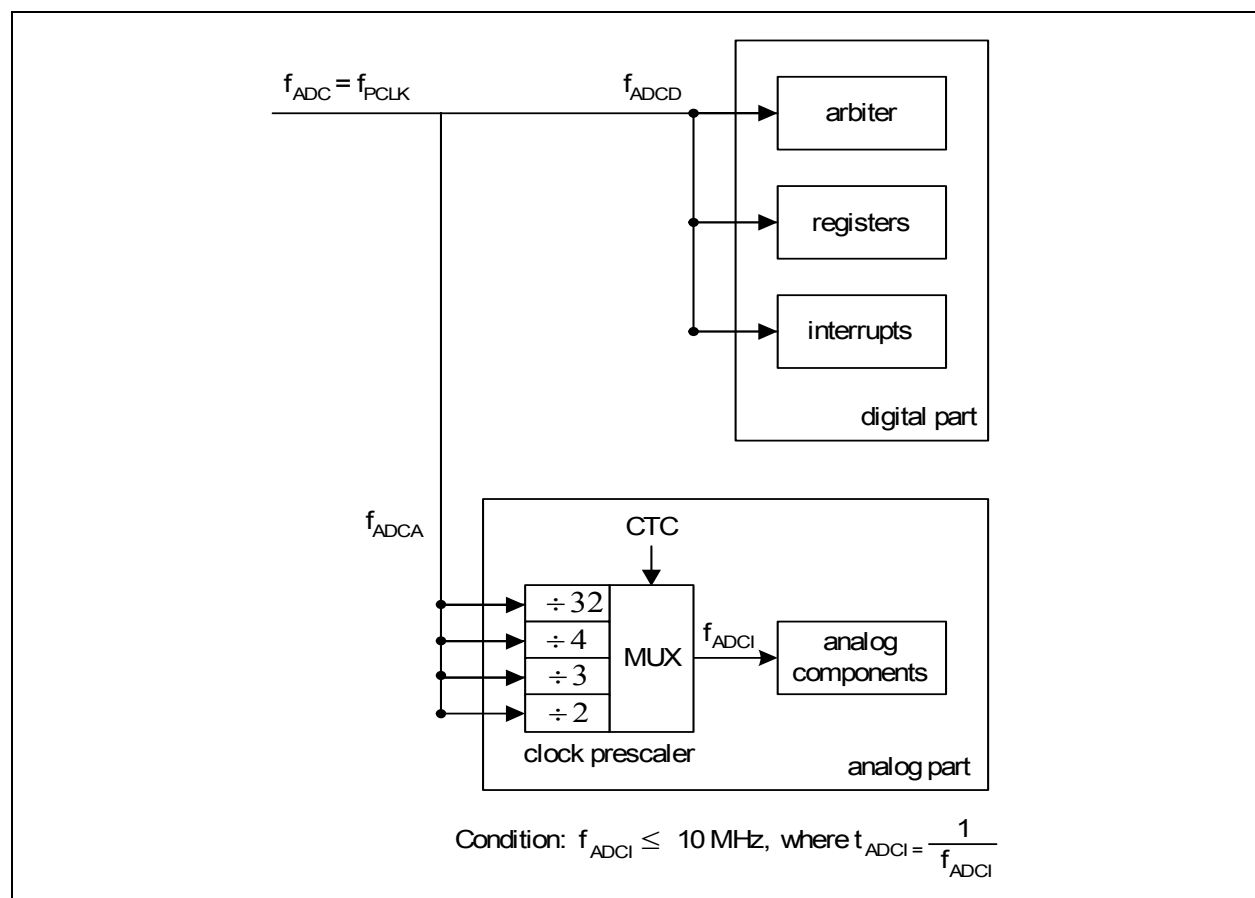


Figure 35 ADC Clocking Scheme

For module clock $f_{ADC} = 24 \text{ MHz}$, the analog clock f_{ADCI} frequency can be selected as shown in [Table 34](#).

Table 34 f_{ADCI} Frequency Selection

Module Clock f_{ADC}	CTC	Prescaling Ratio	Analog Clock f_{ADCI}
24 MHz	00 _B	$\div 2$	12 MHz (N.A)
	01 _B	$\div 3$	8 MHz
	10 _B	$\div 4$	6 MHz
	11 _B (default)	$\div 32$	750 kHz

As f_{ADCI} cannot exceed 10 MHz, bit field CTC should not be set to 00_B when f_{ADC} is 24 MHz. During slow-down mode where f_{ADC} may be reduced to 12 MHz, 6 MHz etc., CTC can be set to 00_B as long as the divided analog clock f_{ADCI} does not exceed 10 MHz.

Electrical Parameters

4.1.2 Absolute Maximum Rating

Maximum ratings are the extreme limits to which the XC886/888 can be subjected to without permanent damage.

Table 4-1 Absolute Maximum Rating Parameters

Parameter	Symbol	Limit Values		Unit	Notes
		min.	max.		
Ambient temperature	T_A	-40	125	°C	under bias
Storage temperature	T_{ST}	-65	150	°C	¹⁾
Junction temperature	T_J	-40	150	°C	under bias ¹⁾
Voltage on power supply pin with respect to V_{SS}	V_{DDP}	-0.5	6	V	¹⁾
Voltage on any pin with respect to V_{SS}	V_{IN}	-0.5	$V_{DDP} + 0.5$ or max. 6	V	whichever is lower ¹⁾
Input current on any pin during overload condition	I_{IN}	-10	10	mA	¹⁾
Absolute sum of all input currents during overload condition	$\Sigma I_{IN} $	—	50	mA	¹⁾

1) Not subjected to production test, verified by design/characterization.

Note: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. During absolute maximum rating overload conditions ($V_{IN} > V_{DDP}$ or $V_{IN} < V_{SS}$) the voltage on V_{DDP} pin with respect to ground (V_{SS}) must not exceed the values defined by the absolute maximum ratings.

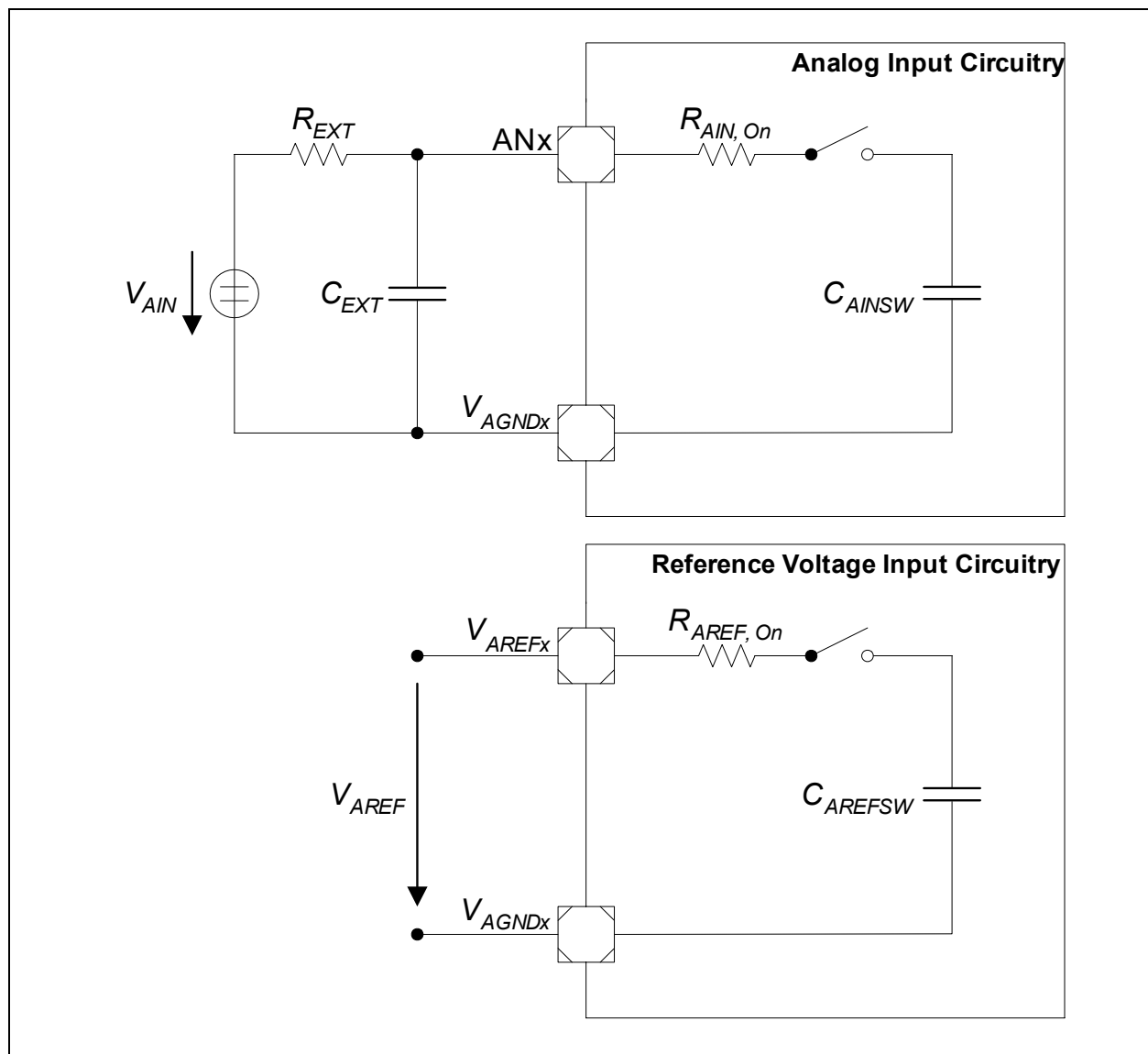


Figure 39 **ADC Input Circuits**

Package and Quality Declaration
5.3 Quality Declaration

Table 2 shows the characteristics of the quality parameters in the XC886/888.

Table 2 Quality Parameters

Parameter	Symbol	Limit Values		Unit	Notes
		Min.	Max.		
ESD susceptibility according to Human Body Model (HBM)	V_{HBM}	-	2000	V	Conforming to EIA/JESD22-A114-B ¹⁾
ESD susceptibility according to Charged Device Model (CDM) pins	V_{CDM}	-	500	V	Conforming to JESD22-C101-C ¹⁾

1) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

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